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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1938t-i-ss

3.5 Stack

All devices have a 16-level x 15-bit wide hardware stack (refer to Figure 3-1). The stack space is not part of either program or data space. The PC is PUSHed onto the stack when CALL or CALLW instructions are executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer if the STVREN bit is programmed to '0' (Configuration Words). This means that after the stack has been PUSHed sixteen times, the seventeenth PUSH overwrites the value that was stored from the first PUSH. The eighteenth PUSH overwrites the second PUSH (and so on). The STKOVF and STKUNF flag bits will be set on an Overflow/Underflow, regardless of whether the Reset is enabled.

Note 1: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, CALLW, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

3.5.1 ACCESSING THE STACK

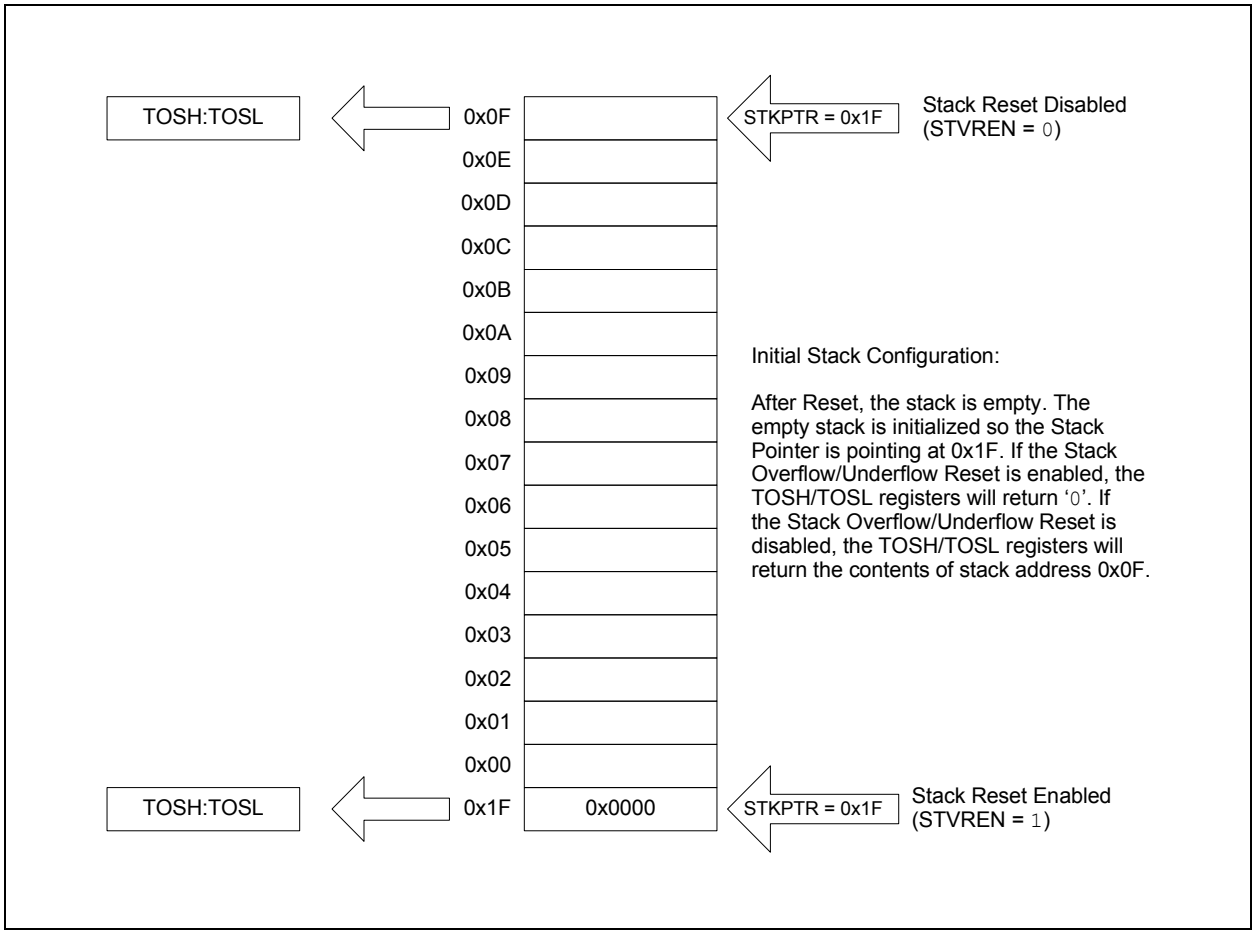
The stack is available through the TOSH, TOSL and STKPTR registers. STKPTR is the current value of the Stack Pointer. TOSH:TOSL register pair points to the TOP of the stack. Both registers are read/writable. TOS is split into TOSH and TOSL due to the 15-bit size of the PC. To access the stack, adjust the value of STKPTR, which will position TOSH:TOSL, then read/write to TOSH:TOSL. STKPTR is 5 bits to allow detection of overflow and underflow.

Note: Care should be taken when modifying the STKPTR while interrupts are enabled.

During normal program operation, CALL, CALLW and Interrupts will increment STKPTR while RETLW, RETURN, and RETFIE will decrement STKPTR. At any time STKPTR can be inspected to see how much stack is left. The STKPTR always points at the currently used place on the stack. Therefore, a CALL or CALLW will increment the STKPTR and then write the PC, and a return will unload the PC and then decrement the STKPTR.

Reference Figure 3-4 through Figure 3-7 for examples of accessing the stack.

FIGURE 3-4: ACCESSING THE STACK EXAMPLE 1



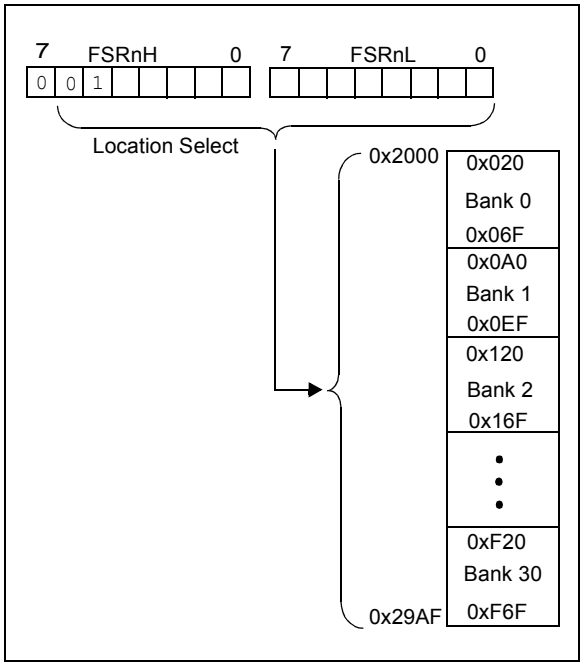
3.6.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

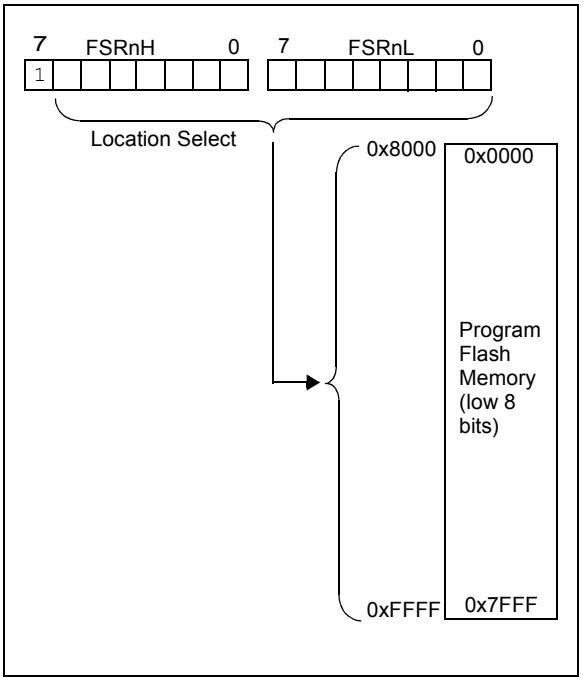
FIGURE 3-10: LINEAR DATA MEMORY MAP



3.6.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-11: PROGRAM FLASH MEMORY MAP



NOTES:

9.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to VDD or VSS externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 6.11 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

11.3.2 ERASING FLASH PROGRAM MEMORY

While executing code, program memory can only be erased by rows. To erase a row:

1. Load the EEADRH:EEADRL register pair with the address of new row to be erased.
2. Clear the CFGS bit of the EECON1 register.
3. Set the EEPGD, FREE, and WREN bits of the EECON1 register.
4. Write 55h, then AAh, to EECON2 (Flash programming unlock sequence).
5. Set control bit WR of the EECON1 register to begin the erase operation.
6. Poll the FREE bit in the EECON1 register to determine when the row erase has completed.

See Example 11-4.

After the "`BSF EECON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

11.3.3 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the starting address of the word(s) to be programmed.
2. Load the write latches with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 11-2 (block writes to program memory with 8 write latches) for more details. The write latches are aligned to the address boundary defined by EEADRL as shown in Table 11-1. Write operations do not cross these boundaries. At the completion of a program memory write operation, the write latches are reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a block of program memory. These steps are divided into two parts. First, all write latches are loaded with data except for the last program memory location. Then, the last write latch is loaded and the programming sequence is initiated. A special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. This unlock sequence should not be interrupted.

1. Set the EEPGD and WREN bits of the EECON1 register.
2. Clear the CFGS bit of the EECON1 register.
3. Set the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`1`', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the EEADRH:EEADRL register pair with the address of the location to be written.
5. Load the EEDATH:EEDATL register pair with the program memory data to be written.
6. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The write latch is now loaded.
7. Increment the EEADRH:EEADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`0`', the write sequence will initiate the write to Flash program memory.
10. Load the EEDATH:EEDATL register pair with the program memory data to be written.
11. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The entire latch block is now written to Flash program memory.

It is not necessary to load the entire write latch block with user program data. However, the entire write latch block will be written to program memory.

An example of the complete write sequence for eight words is shown in Example 11-5. The initial address is loaded into the EEADRH:EEADRL register pair; the eight words of data are loaded using indirect addressing.

Note:	The code sequence provided in Example 11-5 must be repeated multiple times to fully program an erased program memory row.

11.7 Register Definitions: EEPROM and Flash Control

REGISTER 11-1: EEDATL: EEPROM DATA LOW-BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
EEDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEDAT<7:0>**: Read/write value for EEPROM data byte or Least Significant bits of program memory

REGISTER 11-2: EEDATH: EEPROM DATA HIGH-BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	EEDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **EEDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 11-3: EEADRL: EEPROM ADDRESS LOW-BYTE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
EEADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEADR<7:0>**: Specifies the Least Significant bits for program memory address or EEPROM address

REGISTER 11-4: EEADRH: EEPROM ADDRESS HIGH-BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	EEADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '1'

bit 6-0 **EEADR<14:8>**: Specifies the Most Significant bits for program memory address or EEPROM address

TABLE 13-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	131
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	90
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	145
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	145
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	145
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	130

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Interrupt-on-Change.

REGISTER 23-4: CCPxAS: CCPX AUTO-SHUTDOWN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CCPxASE	CCPxAS2	CCPxAS1	CCPxAS0	PSSxAC<1:0>		PSSxBD<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CCPxASE:** CCPx Auto-Shutdown Event Status bit
1 = A shutdown event has occurred; CCPx outputs are in shutdown state
0 = CCPx outputs are operating

bit 6 **CCPxAS2:** CCPx Auto-Shutdown Source 2 Select bit
1 = Auto-shutdown 2 source is enabled, V_{IL} on INT pin
0 = Auto-shutdown 2 source is disabled

bit 5 **CCPxAS1:** CCPx Auto-Shutdown Source 1 Select bit
1 = Auto-shutdown 1 source is enabled, async_CxOUT(1),(2) output low
0 = Auto-shutdown 1 source is disabled

bit 4 **CCPxAS0:** CCPx Auto-Shutdown Source 0 Select bit
1 = Auto-shutdown 0 source is enabled, async_C1OUT(1) output low
0 = Auto-shutdown 0 source is disabled

bit 3-2 **PSSxAC<1:0>:** Pins PxA and PxC Shutdown State Control bits
00 = Drive pins PxA and PxC to '0'
01 = Drive pins PxA and PxC to '1'
1x = Pins PxA and PxC tri-state

bit 1-0 **PSSxBD<1:0>:** Pins PxB and PxD Shutdown State Control bits
00 = Drive pins PxB and PxD to '0'
01 = Drive pins PxB and PxD to '1'
1x = Pins PxB and PxD tri-state

Note 1: If CxSYNC is enabled, the shutdown will be delayed by Timer1.
2: async_CxOUT = async_C2OUT (for CCP1 and CCP2)
async_CxOUT = async_C3OUT (for CCP3)

FIGURE 24-7: SPI DAISY-CHAIN CONNECTION

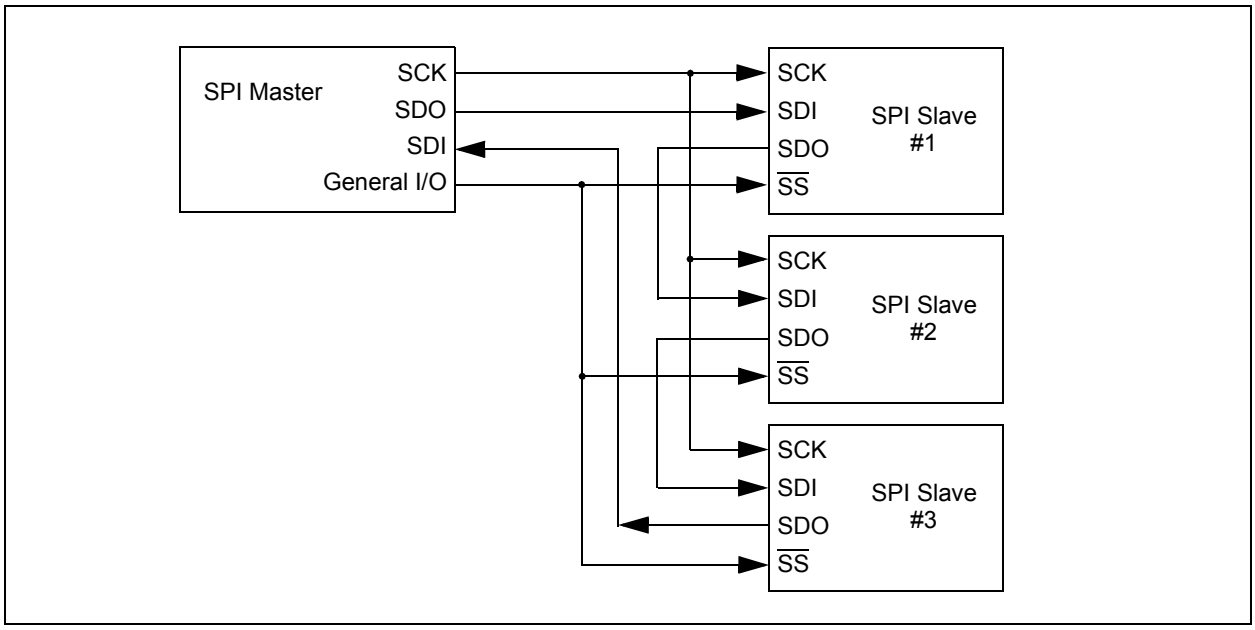


FIGURE 24-8: SLAVE SELECT SYNCHRONOUS WAVEFORM

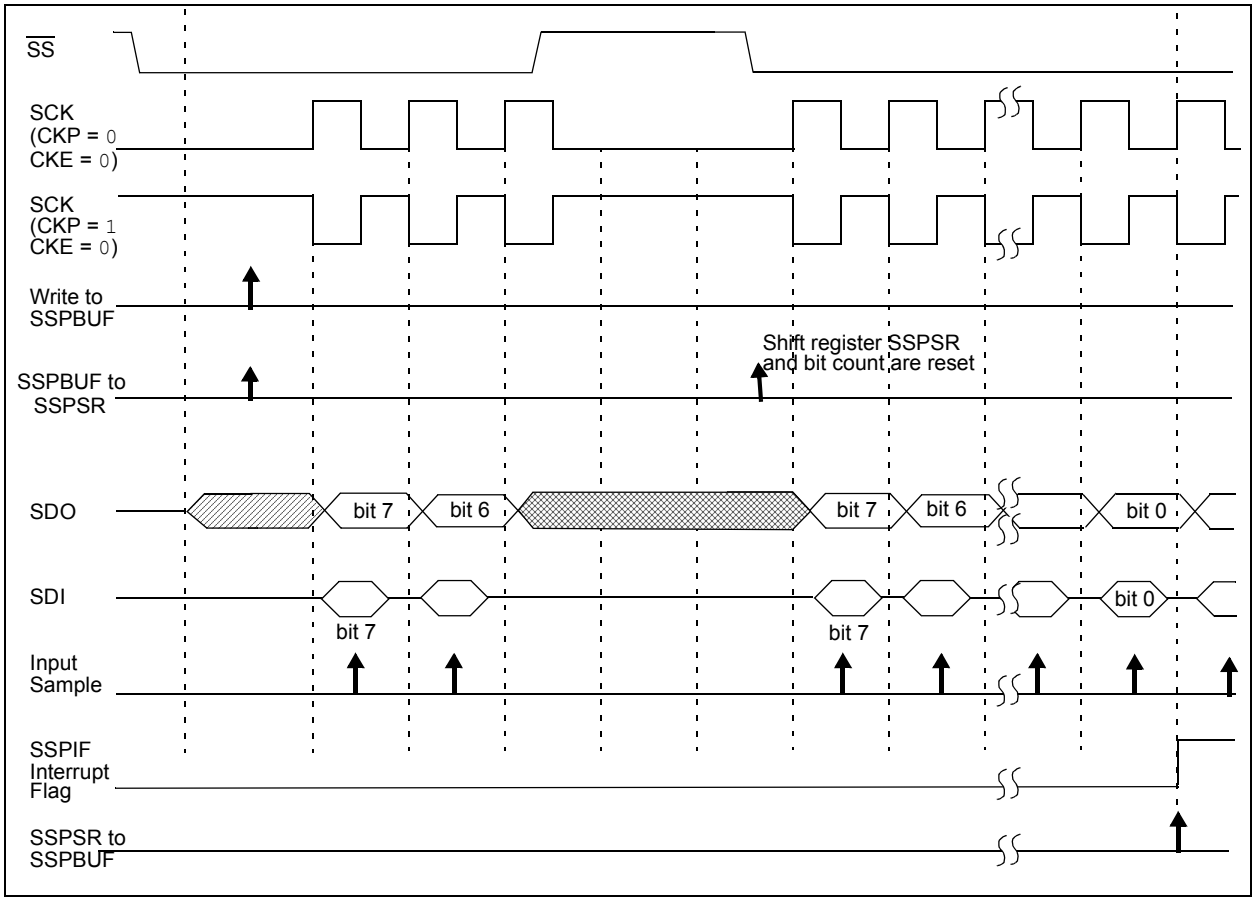
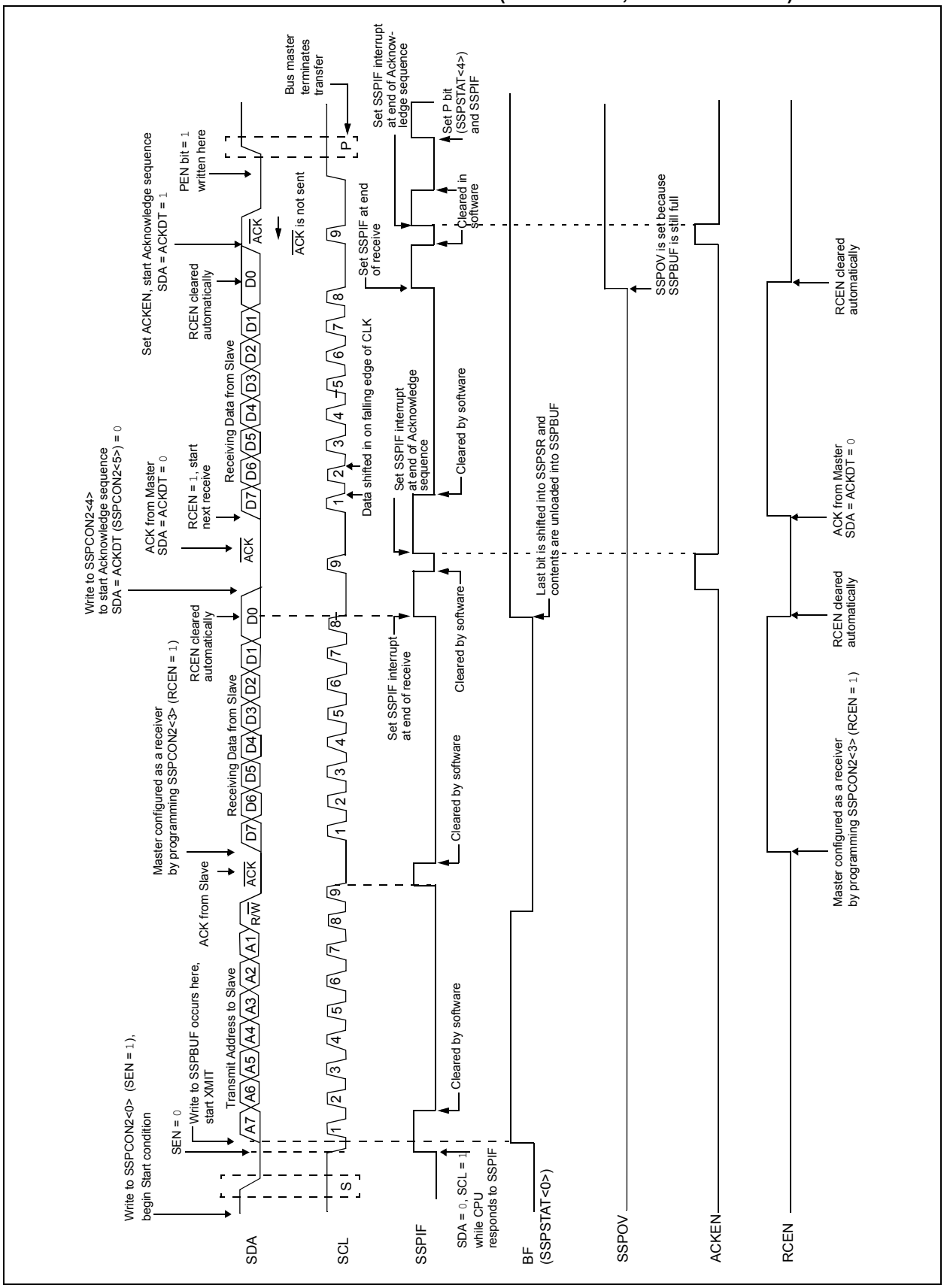


FIGURE 24-29: I²C MASTER MODE WAVEFORM (RECEPTION, 7-BIT ADDRESS)



24.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN bit of the SSPCON2 register. When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP module then goes into Idle mode (Figure 24-30).

24.6.8.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write does not occur).

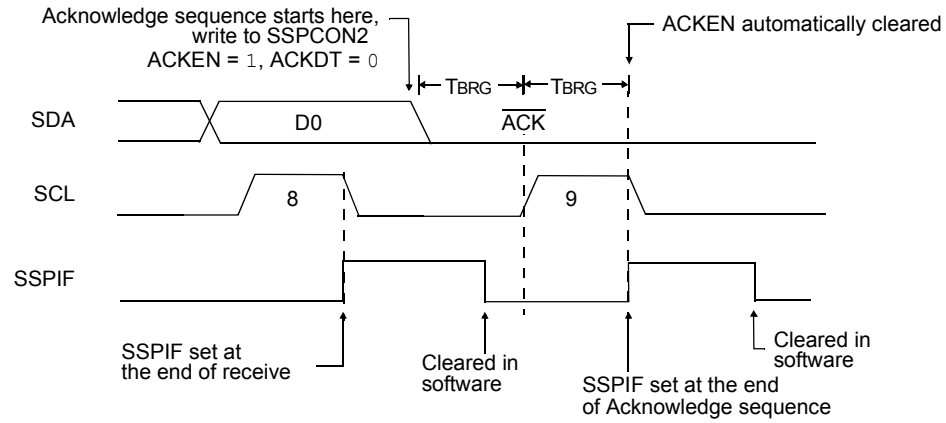
24.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN bit of the SSPCON2 register. At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit of the SSPSTAT register is set. A TBRG later, the PEN bit is cleared and the SSPIF bit is set (Figure 24-31).

24.6.9.1 WCOL Status Flag

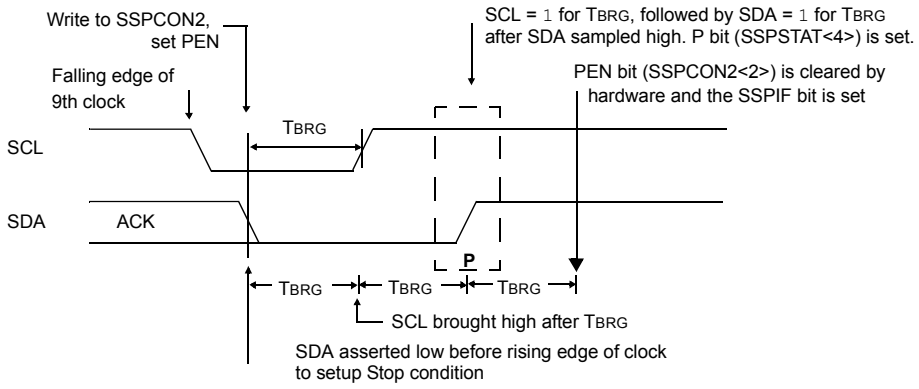
If the user writes the SSPBUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 24-30: ACKNOWLEDGE SEQUENCE WAVEFORM



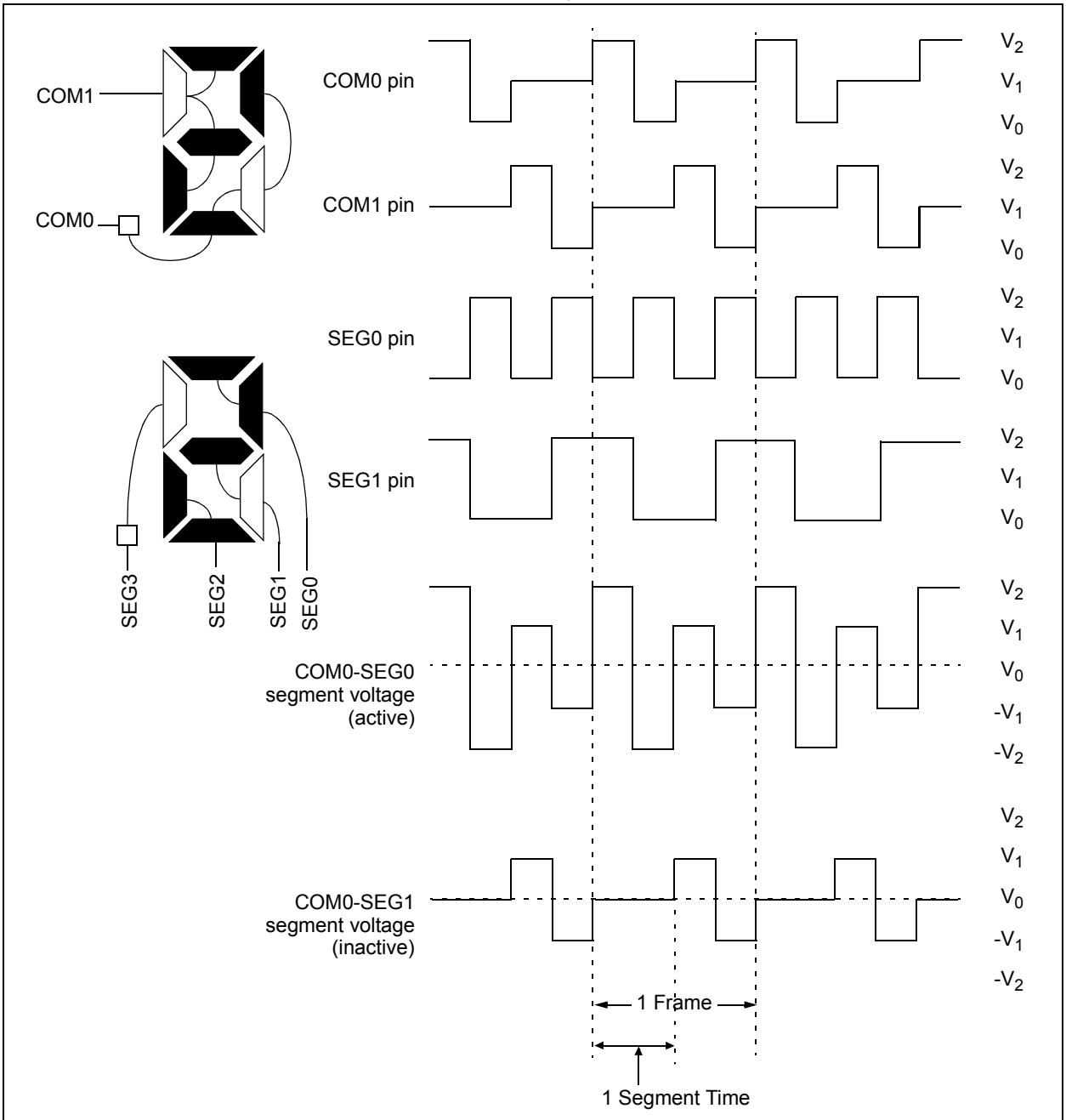
Note: TBRG = one Baud Rate Generator period.

FIGURE 24-31: STOP CONDITION RECEIVE OR TRANSMIT MODE



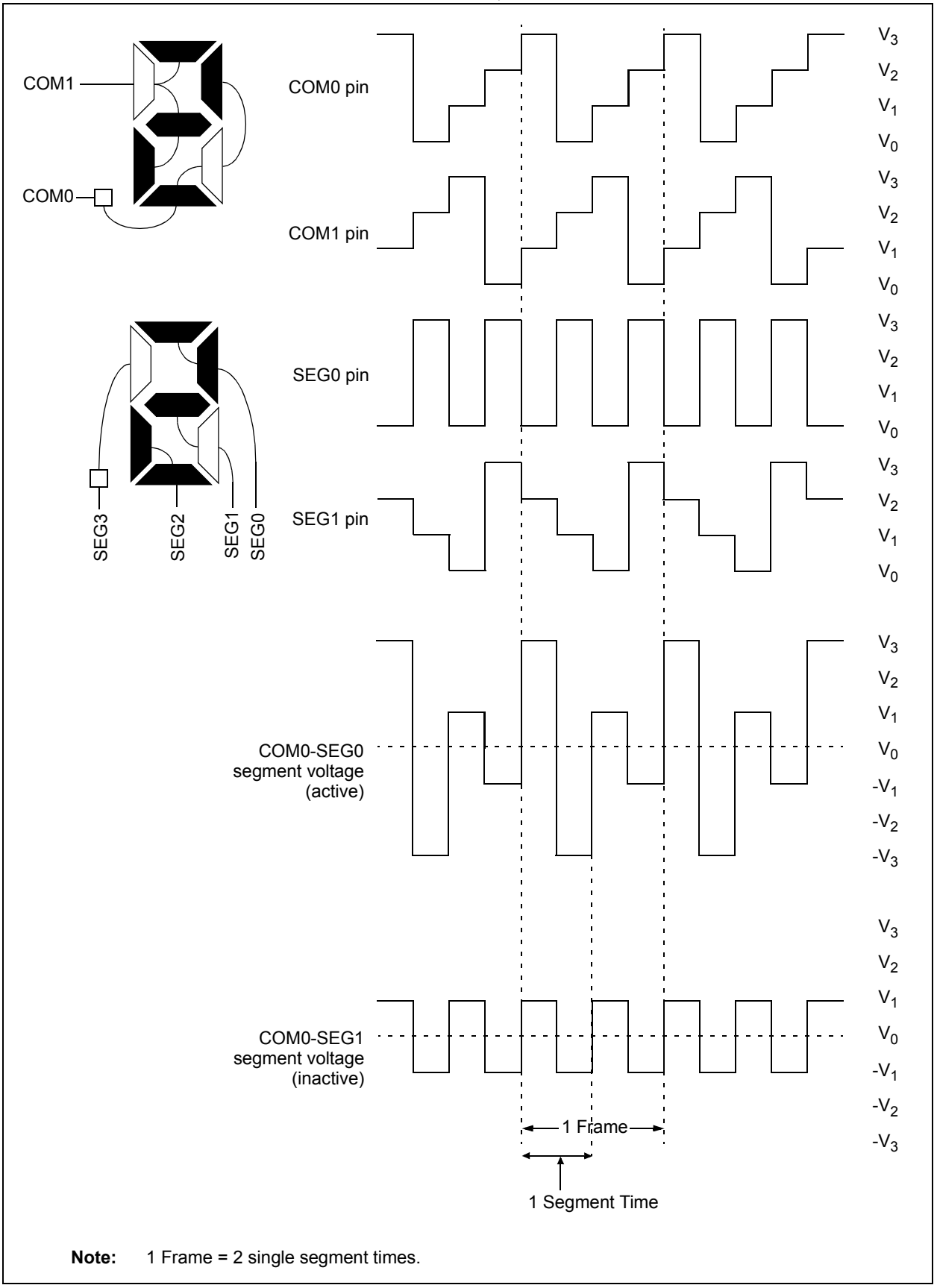
Note: TBRG = one Baud Rate Generator period.

FIGURE 27-9: TYPE-A WAVEFORMS IN 1/2 MUX, 1/2 BIAS DRIVE



Note: 1 Frame = 2 single segment times.

FIGURE 27-11: TYPE-A WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE



Note: 1 Frame = 2 single segment times.

MOVIW **Move INDFn to W**

Syntax: [*label*] MOVIW ++FSRn
[*label*] MOVIW --FSRn
[*label*] MOVIW FSRn++
[*label*] MOVIW FSRn--
[*label*] MOVIW k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: INDFn → W
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)
- Unchanged

Status Affected: Z

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

MOVLB **Move literal to BSR**

Syntax: [*label*] MOVLB k

Operands: 0 ≤ k ≤ 15

Operation: k → BSR

Status Affected: None

Description: The 5-bit literal 'k' is loaded into the Bank Select Register (BSR).

MOVLP **Move literal to PCLATH**

Syntax: [*label*] MOVLP k

Operands: 0 ≤ k ≤ 127

Operation: k → PCLATH

Status Affected: None

Description: The seven-bit literal 'k' is loaded into the PCLATH register.

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W)

Status Affected: None

Description: The eight-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 127

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION_REG
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

FIGURE 31-67: COMPARATOR RESPONSE TIME, NORMAL-POWER MODE, (CxSP = 1)

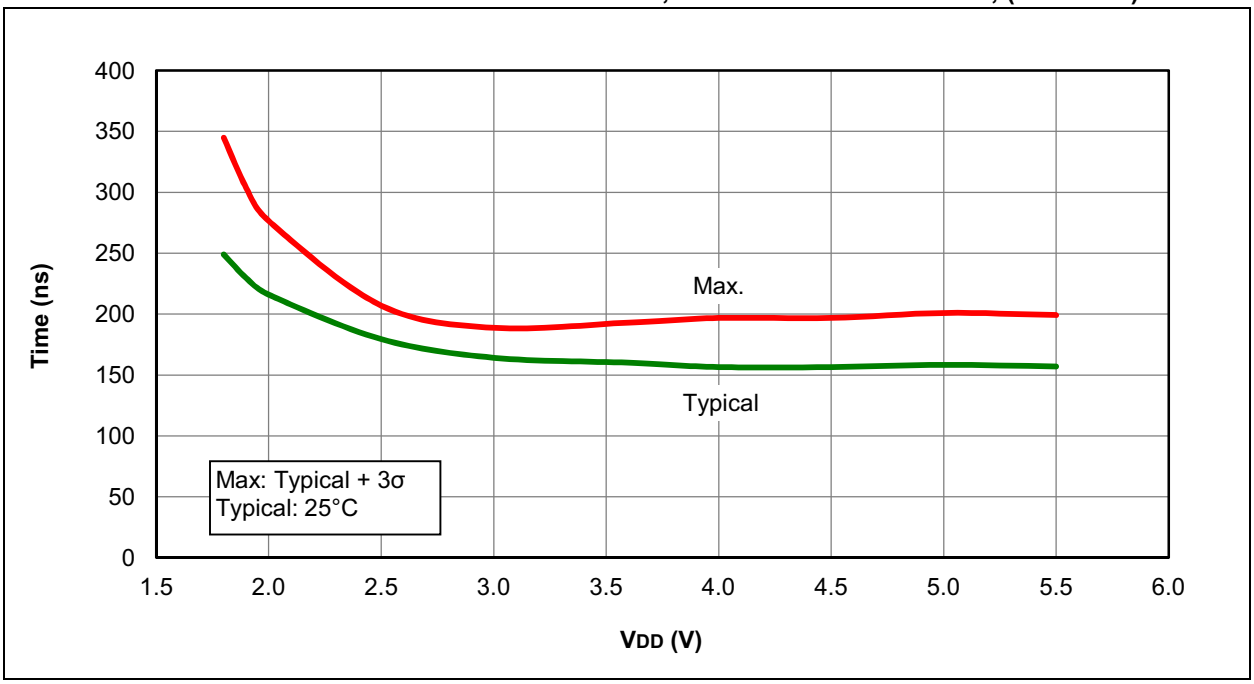
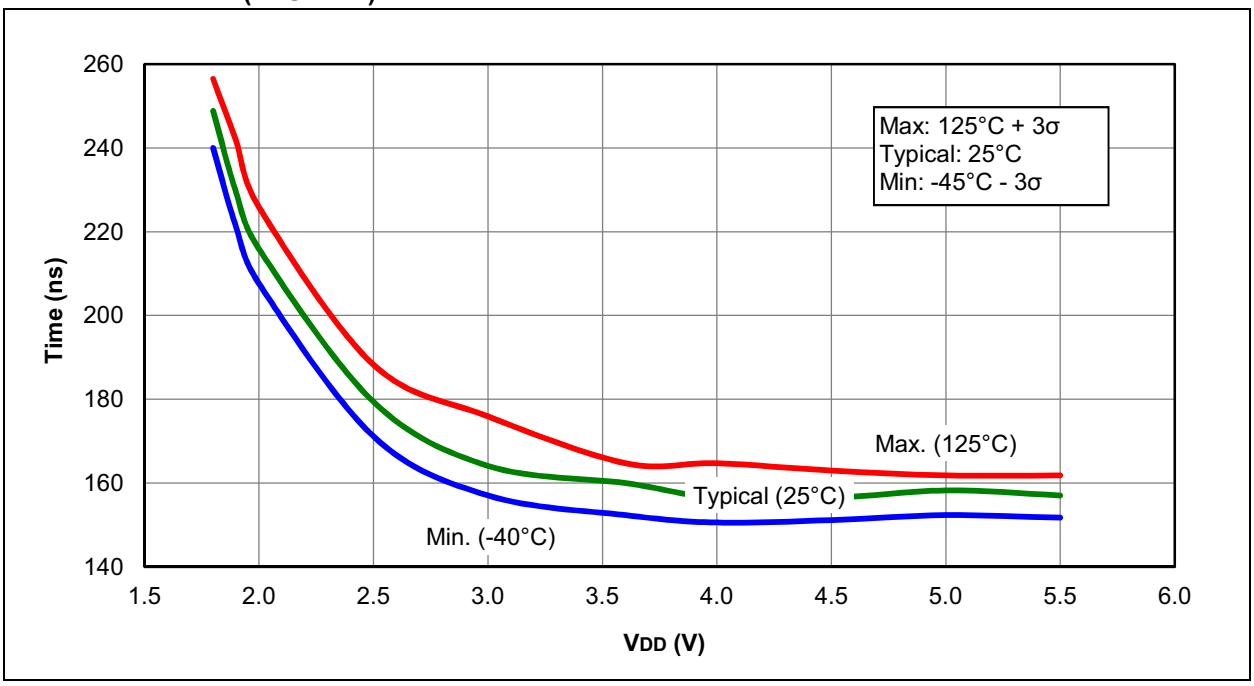


FIGURE 31-68: COMPARATOR RESPONSE TIME OVER TEMPERATURE, NORMAL-POWER MODE (CxSP = 1)



32.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

32.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

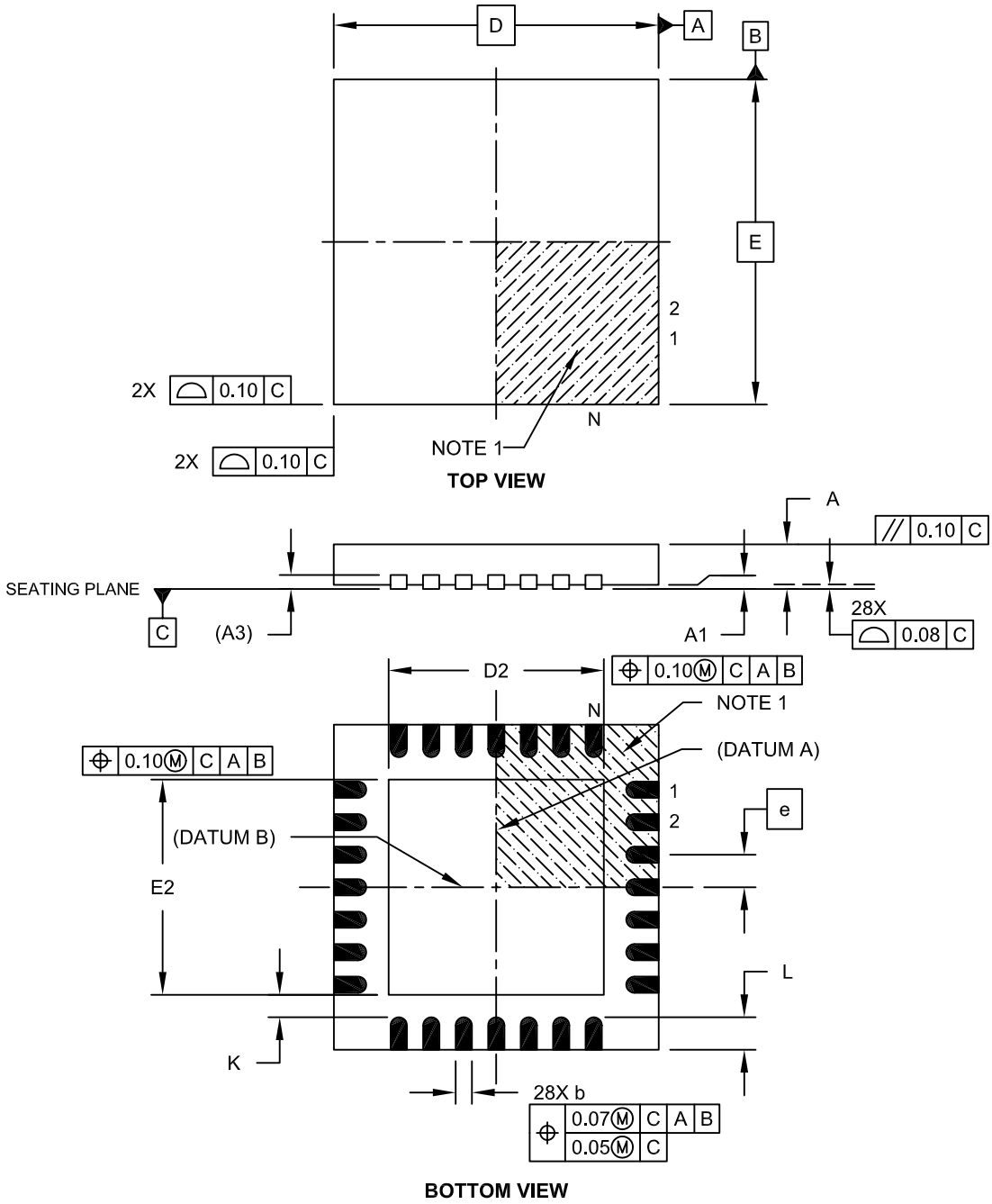
- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

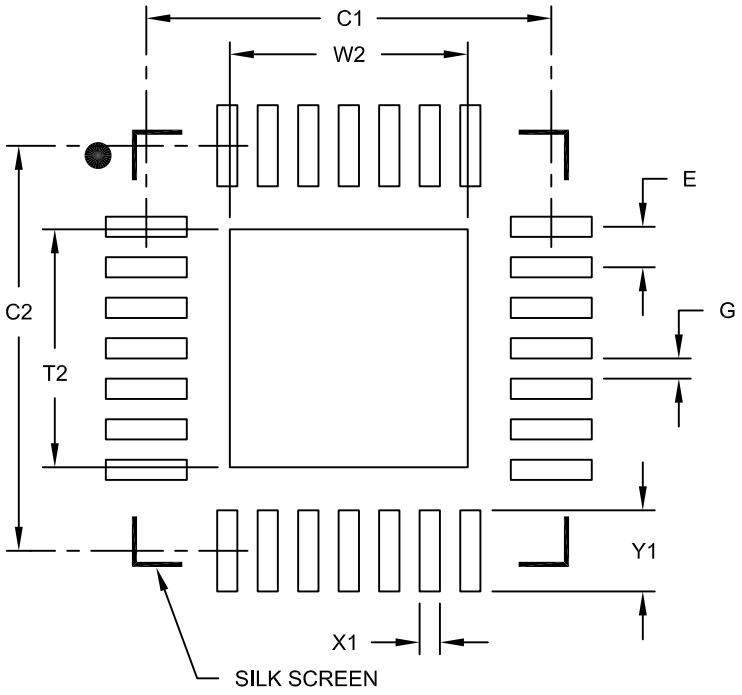
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-152A Sheet 1 of 2

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 4x4 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			2.35
Optional Center Pad Length	T2			2.35
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2152A

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